

MECHANICAL CASE OUTLINE

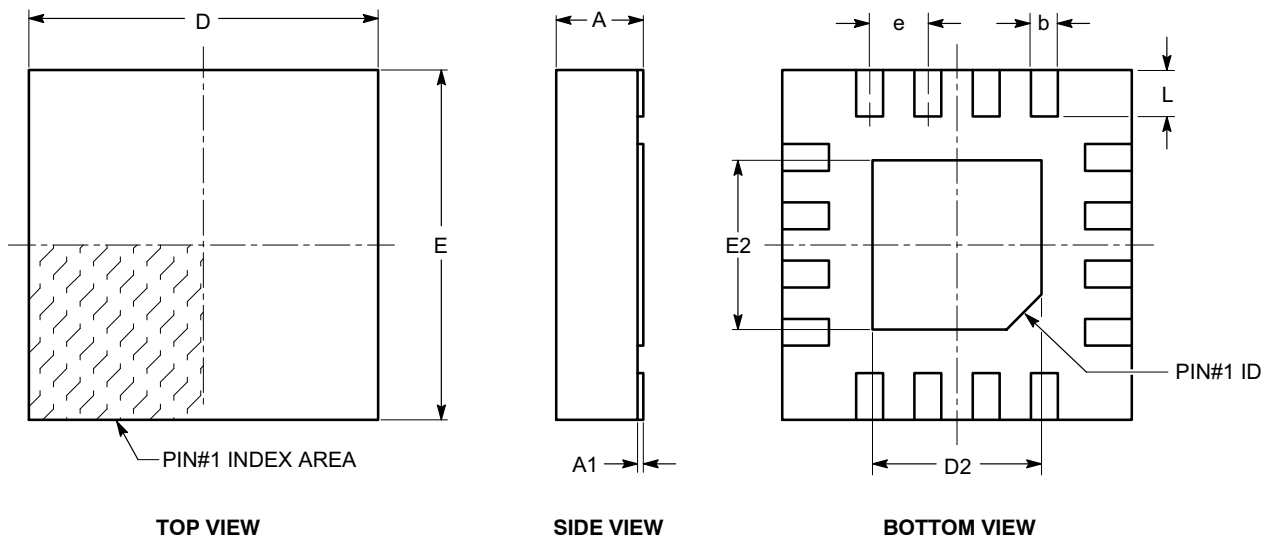
PACKAGE DIMENSIONS

ON Semiconductor®



TQFN16, 3x3
CASE 510AD-01
ISSUE A

DATE 19 MAR 2008



SYMBOL	MIN	NOM	MAX
A	0.70	0.75	0.80
A1	0.00	0.02	0.05
A3	0.20 REF		
b	0.18	0.25	0.30
D	2.90	3.00	3.10
D2	1.40	---	1.80
E	2.90	3.00	3.10
E2	1.40	---	1.80
e	0.50 BSC		
L	0.30	0.40	0.50

Notes:

- (1) All dimensions are in millimeters.
- (2) Complies with JEDEC MO-220.

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